

Electronic Acknowledgement Receipt

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Title of Invention:	ENCAPSULATED PIN STRUCTURE FOR IMPROVED RELIABILITY OF WAFER
First Named Inventor/Applicant Name:	Tien-Jen Cheng
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Amendment After Final	fis920030103amend.pdf	245473	no	9

Warnings:

Information:	Total Files Size (in bytes):	245473
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